



TE0782 TRM

Revision: V12

Date: 10-Feb-2017 11:23

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Overview

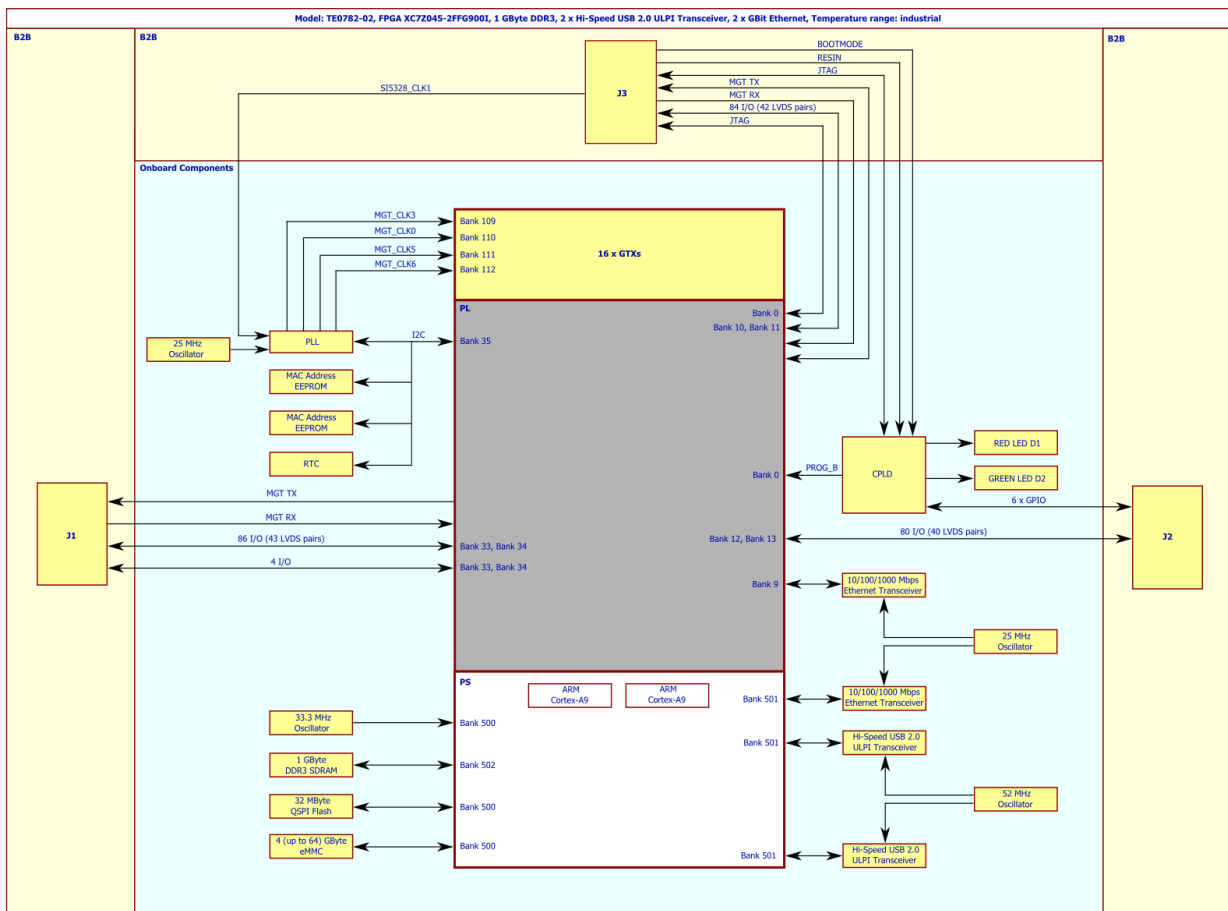
On <https://wiki.trenz-electronic.de/display/PD/TE0782-02+TRM> the online version of this manual and other documents can be found.

The Trenz Electronic TE0782 is a high-performance, industrial-grade SoM (System on Module) with industrial temperature range based on Xilinx Zynq-7000 SoC. It is equipped with a Xilinx Zynq-7 (XC7Z035, XC7Z045 or XC7Z100).

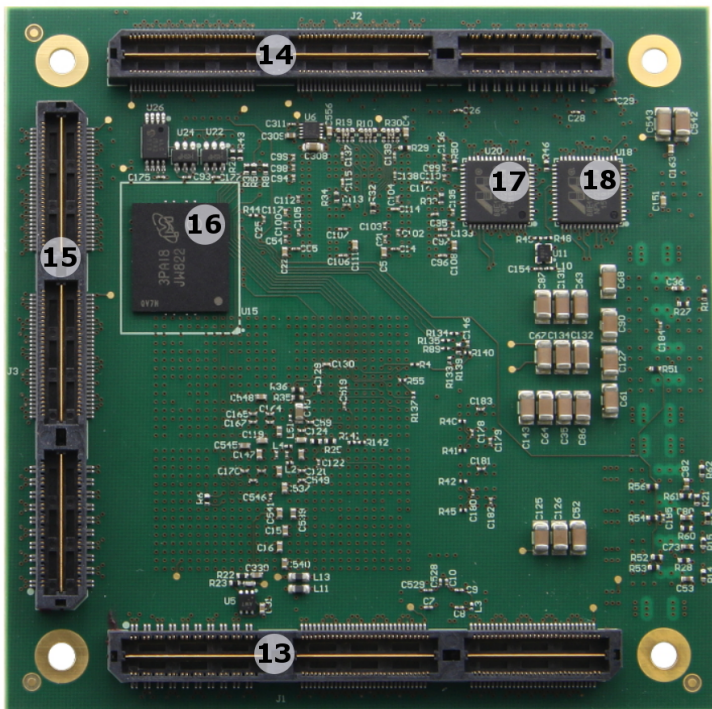
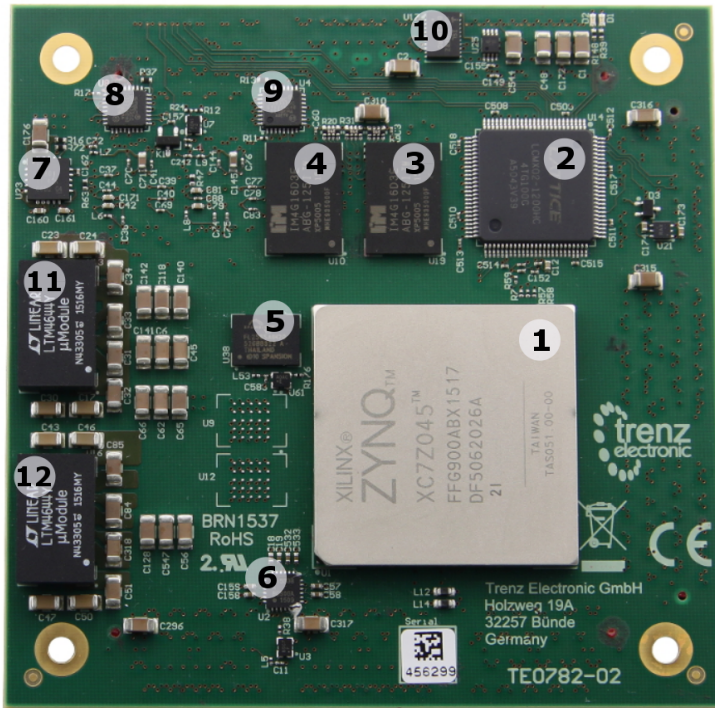
These highly integrated modules with an economical price-performance-ratio have a form-factor of 8,5 x 8,5 cm and are available in several versions.

All parts cover at least industrial temperature range of -40°C to +85°C. The module operating temperature range depends on customer design and cooling solution. Please contact us for options and for modified PCB-equipping due increasing cost-performance-ratio and prices for large-scale order.

Block Diagram



Main Components



The SoM TE0782-02 has following components on board:

1. Xilinx Zynq-7 XC7Z035, XC7Z045 or XC7Z100 SoC
2. Lattice Semiconductor MachXO2 1200HC System Controller CPLD
3. Intelligent Memory 512 MByte DDR3L-1600 SDRAM (8 Banks a 32 MWords, 16 Bit Word-Width)
4. Intelligent Memory 512 MByte DDR3L-1600 SDRAM (8 Banks a 32 MWords, 16 Bit Word-Width)
5. Spansion 32 MByte QSPI Flash Memory
6. SI5338A PLL programmable clock generator
7. TI Low-Dropout Linear Regulator @1.5V
8. Microchip USB3320 USB-Transceiver
9. Microchip USB3320 USB-Transceiver
10. Intersil ISL12020MIRZ Real-Time-Clock
11. LT Quad 4A PowerSoC DC-DC Converter @1.0V
12. LT Quad 4A PowerSoC DC-DC Converter @3.3V, @1,8V, @1.2V_MGT, @1.0V_MGT
13. Samtec ASP-122952-01 160-pin stacking strips (2 rows a 80 positions)
14. Samtec ASP-122952-01 160-pin stacking strips (2 rows a 80 positions)
15. Samtec ASP-122952-01 160-pin stacking strips (2 rows a 80 positions)
16. Micron Technology 4 GByte eMMC
17. Marvell Alaska 88E1512 Gigabit Ethernet PHY
18. Marvell Alaska 88E1512 Gigabit Ethernet PHY

Key Features

- Xilinx Zynq-7 XC7Z035, XC7Z045 or XC7Z100 SoC
- Rugged for shock and high vibration
- large number of configurable I/Os is provided via rugged high-speed stacking strips
- Dual ARM Cortex-A9 MPCore
 - 1 GByte RAM (32-Bit wide DDR3)
 - 32 MByte QSPI Flash memory
 - 2 x Hi-Speed USB2.0 ULPI transceiver PHY
 - 2 x Gigabit (10/100/1000 Mbps) Ethernet transceiver PHY
 - 4 GByte eMMC (optional up to 64GByte)
- 2 x MAC-Address EEPROMs
- optional 2 x 8 MByte HyperRAM (max 2 x 32 MByte HyperRAM) or optional 2 x 64 MByte HyperFLASH
- Temperature compensated RTC (real-time clock)
- Si5338 PLL for GTX Transceiver clocks
- Plug-on module with 3 x 160-pin high-speed strips
 - 16 GTX high-performance transceiver
 - GT transceiver clock inputs
 - 254 FPGA I/O's (125 LVDS pairs)
- On-board high-efficiency switch-mode DC-DC converters
- System management
- eFUSE bit-stream encryption
- AES bit-stream encryption
- Evenly-spread supply pins for good signal integrity
- User LED

Assembly options for cost or performance optimization available upon request.

Signals, Interfaces and Pins

System Controller CPLD I/O-Pins

Special purpose pins to configure and operate the System Controller CPLD (IC U14) used by TE0782:

Name	Connection	Note
CLPD_GPIO7	B2B	Function defined by CPLD Firmware (legacy name was BOOTMODE)
CLPD_GPIO6	B2B	Function defined by CPLD Firmware (legacy name was CONFIGX)
JTAGENB	B2B	logic high enables CPLD JTAG pins, if low CPLD update is disabled
nRST_IN	B2B	active low System-reset input (old name RESIN)
CLPD_GPIO0	B2B	Function defined by CPLD Firmware
CLPD_GPIO1	B2B	Function defined by CPLD Firmware
CLPD_GPIO2	B2B	Function defined by CPLD Firmware
CLPD_GPIO3	B2B	Function defined by CPLD Firmware
CLPD_GPIO4	B2B	Function defined by CPLD Firmware
CLPD_GPIO5	B2B	Function defined by CPLD Firmware
CPLD_IO	PL	

Small CPLD controls some functions of the SoM, this CPLD can be updated by the end user if support is designed in on customer base.

Boot Modes

TE0782 supports primary boot from

- SPI Flash

Boot from on-board eMMC is also supported as secondary boot (FSBL must be loaded from SPI Flash).

JTAG Bootmode is always possible no matter the Zynq Boot mode selected.

JTAG

JTAG access to the Xilinx Zynq-7000 device is provided by connector J3.

Signal	B2B Pin
TCK	J3: 141
TDI	J3: 147
TDO	J3: 148
TMS	J3: 1142

CPLD-JTAG access to the Xilinx Zynq-7000 device is provided by connector J3.

Signal	B2B Pin
M_TCK	J3: 81
M_TDI	J3: 87
M_TDO	J3: 82
M_TMS	J3: 88



JTAGENB pin in J3 should be kept low or grounded for normal operation.

Clocking

Silabs Multisynth PLL Si5338 can deliver GT reference clocks to all 4 GT Banks. Additionally a GT Reference clock can be generated on the base board for any of the 4 GT Banks. There is reference clock available on the TE0782 for Si5338, optionally external reference clock can be supplied from the base.

Clock	Frequency	IC	Zynq PS / PL	Notes
PS CLK	33.3333 MHz	U61	PS CLK	PS Subsystem main clock
10/100/1000 Mbps ETH PHYs reference	25 MHz	U11	-	
USB PHY reference	52 MHz	U7	-	
PLL reference	25 MHz	U3	-	
GT REFCLK1	-	B2B connector	BANK110, Pin AC7/AC8	Externally supplied from base
GT REFCLK4	-	B2B connector	BANK111, Pin U7/U8	Externally supplied from base
Si5338 CLK0		U2	BANK110, Pin AA8/AA7	
Si5338 CLK1		U2	BANK109, Pin AF10/AF9	
Si5338 CLK2		U2	BANK111, Pin W8/W7	
Si5338 CLK3		U2	BANK112, Pin N8/N7	

Processing System (PS) Peripherals

Peripheral	IC	Designator	Zynq PS / PL	MIO	Notes
QSPI Flash	S25FL256SAGBHI20	U38	PS QSPI0	MIO1...MIO6	-
ETH0 10/100/1000 Mbps PHY	88E1512-A0-NNP2I000	U18	PS ETH0	MIO16...MIO27, MIO52, MIO53	-
ETH0 10/100/1000 Mbps PHY Reset			PS GPIO	MIO7	ETH1_RESET33 (MIO7) -> CPLD -> ETH1_RESET
ETH1 10/100/1000 Mbps PHY	88E1512-A0-NNP2I000	U20	BANK9, BANK35	-	PHY can be used with soft Ethernet MAC IP also
ETH1 10/100/1000 Mbps PHY Reset			BANK35, Pin B15	-	-
USB0	USB3320C-EZK	U4	PS USB0	MIO28...MIO39	-
USB0 Reset			PS GPIO	MIO0	OTG_RESET33 (MIO0) -> CPLD -> OTG_RESET
USB1	USB3320C-EZK	U8	USB1	MIO40...MIO51	-
USB1 Reset			PS GPIO	MIO0	OTG_RESET33 (MIO0) -> CPLD -> OTG_RESET
Clock PLL	Si5338	U2	BANK35, Pin L14 /L15		Low jitter phase locked loop
e-MMC (embedded e-MMC)	MTFC4GMVEA-4M IT	U15	SDIO0	MIO10...MIO15	-
HyperFlash RAM	S26KS512SDPBHI00x	U9	BANK35	-	optional 2 x 8 MByte HyperRAM (max 2 x 32 MByte HyperRAM) or optional 2 x 64 MByte HyperFLASH
HyperFlash RAM	S26KS512SDPBHI00x	U12	BANK35	-	as above
EEPROM I2C	24LC128-I/ST	U26	BANK35, Pin L14 /L15	-	-
EEPROM I2C	24AA025E48T-I/OT	U22	BANK35, Pin L14 /L15	-	MAC Address
EEPROM I2C	24AA025E48T-I/OT	U24	BANK35, Pin L14 /L15	-	MAC Address
RTC	ISL12020MIRZ	U17	BANK35, Pin L14 /L15	-	Temperature compensated real time clock
RTC Interrupt	ISL12020MIRZ	U17	-	-	RTC_INT -> CPLD

Peripheral	IC	Designator	Zynq PS / PL	MIO	Notes
UART			PS UART	MIO8, MIO9	forwarded to B2B by SC CPLD

Default MIO mapping

MIO	Configured as	B2B	Notes
0	USB Reset	-	CPLD used as level translator
1	QSPI0	-	SPI Flash-CS
2	QSPI0	-	SPI Flash-DQ0
3	QSPI0	-	SPI Flash-DQ1
4	QSPI0	-	SPI Flash-DQ2
5	QSPI0	-	SPI Flash-DQ3
6	QSPI0	-	SPI Flash-SCK
7	Ethernet Reset	-	CPLD used level translator
8	UART TX	JC3:129	output, muxed to B2B by the SC CPLD
9	UART RX	JC3:135	input, muxed to B2B by the SC CPLD
10	SDIO1 D0	-	-
11	SDIO1 CMD	-	-
12	SDIO1 CLK	-	-
13	SDIO1 D1	-	-
14	SDIO1 D2	-	-
15	SDIO1 D3	-	-
16..27	ETH0	-	Ethernet RGMII PHY
28..39	USB0	-	USB0 ULPI PHY
40...51	USB1	-	USB1 ULPI PHY
52	ETH0 MDC	-	-
53	ETH0 MDIO	-	-

Pin Definitions

Pins named `_vrn` and `_vrp` are connected to ZYNQ PL HP Bank special purpose pins VRN/VRP. If needed they can be connected to DCI calibration resistors on the base. If not, then those pins can be used as general purpose I/O.

Bank B35 has 100 ohm DCI calibration resistors installed on TE0782, it is also possible to "borrow" the DCI calibration from B35 for banks B34, and B33. For detailed usage of the DCI check Xilinx documentation.

I2C Interface

The on-board I2C components are connected to BANK35, Pin L15 (I2C_SDA) and to BANK35, Pin L14 (I2C_SCL).

I2C addresses for on-board components

Device	IC	Designator	I2C-Address	Notes
EEPROM	24LC128-I/ST	U26	0x53	user data, parameter
EEPROM	24AA025E48T-I/OT	U22	0x50	MAC Address/EEPROM
EEPROM	24AA025E48T-I/OT	U24	0x51	MAC Address/EEPROM
RTC	ISL12020MIRZ	U17	0x6F	Temperature compensated real time clock
Battery backed RAM	ISL12020MIRZ	U17	0x57	integrated in RTC
PLL	SI5338A-B-GMR	U2	0x70	
CPLD	LCMXO2-1200HC-4TG100I	U14	user	-

B2B I/O

Number of I/O's connected to the SoC's I/O bank and B2B connector

Bank	Type	VCCIO Max	Connector	IO count	Differential	IO Voltage	Notes
10	HR	3.3V	J3	44	22	user	
11	HR	3.3V	J3	40	20	user	
12	HR	3.3V	J2	40	20	user	
13	HR	3.3V	J2	40	20	user	
33	HP	1.8V	J1	48	23	user	
34	HP	1.8V	J1	42	20	user	

For detailed information about the pin out, please refer to the [Master Pinout Table](#).

Peripherals

LEDs

D1 - Onboard RED LED

Frequency of LED-Toggling [1/2.6sec]	Status
1	Power problem
2	MGT Power problem
3	Reset from base board
4	FPGA not programmed

This function depend on the CPLD revision.

D2 - On-board GREEN LED

Green LED connected to MIO8

Ethernet

The TE0782 is equipped with two Marvell Alaska 88E1512 Gigabit Ethernet PHYs (U18 (ETH1) and U20 (ETH2)). The transceiver PHY of ETH1 is connected to the Zynq PS Ethernet GEM0. The I/O Voltage is fixed at 1.8V. The reference clock input for both PHYs is supplied from an on board 25MHz oscillator (U11).

ETH1 PHY connection:

PHY PIN	ZYNQ PS / PL	System Controller CPLD	Notes
MDC/MDIO	MIO52, MIO53	-	-
LED0	BANK35, Pin B12	-	-
LED1	BANK35, Pin C12	-	-
Interrupt	BANK35, Pin A15	-	-
CONFIG	BANK35, Pin F14	-	-
RESETn	-	Pin 53	ETH1_RESET33 (MIO7) -> CPLD -> ETH1_RESET
RGMII	MIO16..MIO27		-
MDI	-	-	on B2B J2 connector

ETH2 PHY connection:

PHY PIN	Zynq PS / PL	System Controller CPLD	Notes
MDC /MDIO	BANK35, Pin C17/B17	-	-
LED0	BANK35, Pin K15	-	-
LED1	BANK35, Pin B16	-	-
Interrupt	BANK35, Pin A17	-	-
CONFIG	BANK35, Pin E15	-	Pin connected to GND, PHY Address is strapped to 0x00 by default
RESETn	BANK35, Pin B15	-	-
RGMII	BANK9	-	-
MDI	-	-	-

USB

The TE0782 is equipped with two USB PHY's USB3320 from Microchip (U4 (USB0) and U8 (USB1)). The ULPI interface of USB0 is connected to the Zynq PS USB0, ULPI interface of USB1 to Zynq PS USB1. The I/O Voltage is fixed at 1.8V.

The reference clock input of both PHY's is supplied from an on board 52MHz oscillator (U7).

USB0 PHY connection:

PHY Pin	Zynq PS / PL	CPLD	B2B Name (J2)	Notes
ULPI	MIO28..39	-	-	Zynq USB0 MIO pins are connected to the PHY
REFCLK	-	-	-	52MHz from on board oscillator (U7)
REFSEL[0..2]	-	-	-	000 GND, select 52MHz reference Clock
RESETB	MIO0	OTG_RESET33	-	OTG_RESET33 -> CPLD -> OTG_RESET
CLKOUT	MIO36	-	-	Connected to 1.8V selects reference clock operation mode
DP,DM	-	-	USB1_D_P, USB1_D_N	USB Data lines
CPEN	-	-	VBUS1_V_EN	External USB power switch active high enable signal
VBUS	-	-	USB1_VBUS	Connect to USB VBUS via a series resistor. Check reference schematic
ID	-	-	OTG1_ID	For an A-Device connect to ground, for a B-Device left floating

USB1 PHY connection:

PHY Pin	ZYNQ PS / PL	CPLD	B2B Name (J2)	Notes
ULPI	MIO40..51	-	-	Zynq USB1 MIO pins are connected to the PHY
REFCLK	-	-	-	52MHz from on board oscillator (U7)
REFSEL[0..2]	-	-	-	000 GND, select 52MHz reference Clock
RESETB	MIO0	OTG_RESET33	-	OTG_RESET33 -> CPLD -> OTG_RESET
CLKOUT	MIO48	-	-	Connected to 1.8V selects reference clock operation mode
DP,DM	-	-	USB2_D_P, USB2_D_N	USB Data lines
CPEN	-	-	VBUS2_V_EN	External USB power switch active high enable signal
VBUS	-	-	USB2_VBUS	Connect to USB VBUS via a series resistor. Check reference schematic
ID	-	-	OTG2_ID	For an A-Device connect to ground, for a B-Device left floating

The schematic for the USB connector and required components is different depending on the USB usage. USB standard A or B connectors can be used for Host or Device modes. A Mini USB connector can be used for USB Device mode. A USB Micro connector can be used for Device mode, OTG Mode or Host Mode.

RTC

An Intersil temperature compensated real time clock IC ISL12020MIRZ is used for timekeeping (U17). Battery voltage must be supplied to the module from the main board.

Battery backed registers are accessed at I2C slave address 0x57.

General purpose RAM is accessed at I2C slave address 0x6F.

This RTC IC is supported in Linux so it can be used as hwclock device.

PLL

The TE0782 is also equipped with a Silicon Labs I2C-programmable clock generator Si5338A (U2). The Si5338 can be programmed using the I2C-bus, to change the frequency on its outputs. It is accessible on the I2C slave address 0x70.

PLL connection:

Input/Output	Default Frequency	Notes
IN1/IN2	Externally supplied	need decoupling on base board
IN3	25MHz	Fixed input clock
CLK0 A/B	-	GT REFCLK0
CLK1 A/B	-	GT REFCLK3
CLK2 A/B	-	GT REFCLK6
CLK3 A/B	-	GT REFCLK5

MAC-Address EEPROM's

Two Microchip 24AA025E48 EEPROM's (U22 and U24) are used on the TE0782. They contain globally unique 48-bit node addresses, that are compatible with EUI-48(TM) and EUI-64(TM). The devices are organized as two blocks of 128 x 8-bit memory. One of those blocks stores the 48-bit node address and is write protected, the other block is available for application use. Those are accessible by the I2C slave address 0x50 for MAC-Address1 (U22), 0x51 for MAC-Address2 (U24) .

Power

Input Power Supply

Power Rail	Net name	Voltage	I max	Notes
Standby power	C3.3V	3.3V	100mA	System Control CPLD Power
Main power	VIN	12V	TBD	Main power for all on-board DCDC Regulators

Bank Voltages


Bank	Voltage	max. Value	note
0	3.3 V	-	FPGA Configuration
502	1.5 V	-	DDR3-RAM Port
109 / 110 / 111 / 112	1.2 V	-	FPGA MGT
500 / 501	3.3 V	-	MIO Banks
9	1.8 V	-	ETH2 RGMII
10	user	3.3 V	B2B name: VCCIO_10
11	user	3.3 V	B2B name: VCCIO_11
12	user	3.3 V	B2B name: VCCIO_12
13	user	3.3 V	B2B name: VCCIO_13
33	user	1.8 V	B2B name: VCCIO_33
34	user	1.8 V	B2B name: VCCIO_34
35	1.8 V	-	Hyper-RAM, Ethernet, I2C

Power-up sequence at start-up

The Trenz TE0782 SoM is equipped with two quad DC/DC-voltage-regulators to generate the required on-board voltages with the values 1V, 3.3V, 1.8V, 1.2V_MGT, 1V_MGT.

There are also additional voltage regulators on board to generate the voltages 1.5V, VTT, VTTREF and 1.8 V_MGT.

On this SoM the sequence of powering up of the required on-board voltages is handled internally by the system controller CPLD processing the "POWER GOOD"-signals from the voltage-regulators.

 To avoid any damages to the SoM, check for stabilized on-board voltages in steady state before powering up the SoC's I/O bank voltages VCCIO.

The "POWER GOOD"-signals can be checked on the system controller CPLD.

Pay attention to the voltage level of the I/O-signals, which must not be higher than 5V.

Initial Delivery state

Storage device name	Content	Notes
24LC128-I/ST	not programmed	User content
24AA025E48 EEPROM's	User content not programmed	Valid MAC Address from manufacturer
e-MMC Flash-Memory	Empty, not programmed	Except serial number programmed by flash vendor
SPI Flash OTP Area	Empty, not programmed	Except serial number programmed by flash vendor
SPI Flash Quad Enable bit	Programmed	
SPI Flash main array	demo design	
HyperFlash RAM	not programmed	
EFUSE USER	Not programmed	
EFUSE Security	Not programmed	

Variants Currently In Production

Module Variant	Zynq SoC	SoC Junction Temperature	Operating Temperature Range
TE0782-02-035-2I	XC7Z035-2FFG900I	-40°C to 100°C	Industrial grade
TE0782-02-045-2I	XC7Z045-2FFG900I	-40°C to 100°C	Industrial grade
TE0782-02-100-2I	XC7Z100-2FFG900I	-40°C to 100°C	Industrial grade

Technical Specification

Absolute Maximum Ratings

Parameter	Min	Max	Units	Notes
Vin supply voltage	-0.3	15	V	
Vin33 supply voltage	-0.5	3.75	V	
VBat supply voltage	-0.3	6	V	
PL IO Bank supply voltage for HR I/O banks (VCCO)	-0.5	3.6	V	
I/O input voltage for HP I/O banks	-0.55	VCCO_X+0.55	V	
Voltage on Module JTAG pins	-0.4	VCCO_0+0.55	V	VCCO_0 is 3.3V nominal
Storage Temperature	-40	+85	C	
Storage Temperature without the ISL12020MIRZ	-55	+100	C	



Assembly variants for higher storage temperature range on request

Recommended Operating Conditions

Parameter	Min	Max	Units	Notes	Reference document
Vin supply voltage	11.4	12.6	V		
Vin33 supply voltage	3.135	3.465	V		
VBat supply voltage	1.8	5.5	V		
PL IO Bank supply voltage for HR I/O banks (VCCO)	1.14	3.465	V		Xilinx document DS191
I/O input voltage for HR I/O banks	(*)	(*)	V	(*) Check datasheet	Xilinx document DS191 and DS187
Voltage on Module JTAG pins	3.135	3.465	V	VCCO_0 is 3.3 V nominal	



Please check Xilinx Datasheet for complete list of Absolute maximum and recommended operating ratings for the Zynq device (DS181 Artix or DS182 Kintex).

Operating Temperature Ranges

Commercial grade modules

All parts are at least commercial temperature range of 0°C to +70°C. The module operating temperature range depends on customer design and cooling solution. Please contact us for options.

Industrial grade modules

All parts are at least industrial temperature range of -40°C to +85°C. The module operating temperature range depends on customer design and cooling solution. Please contact us for options.

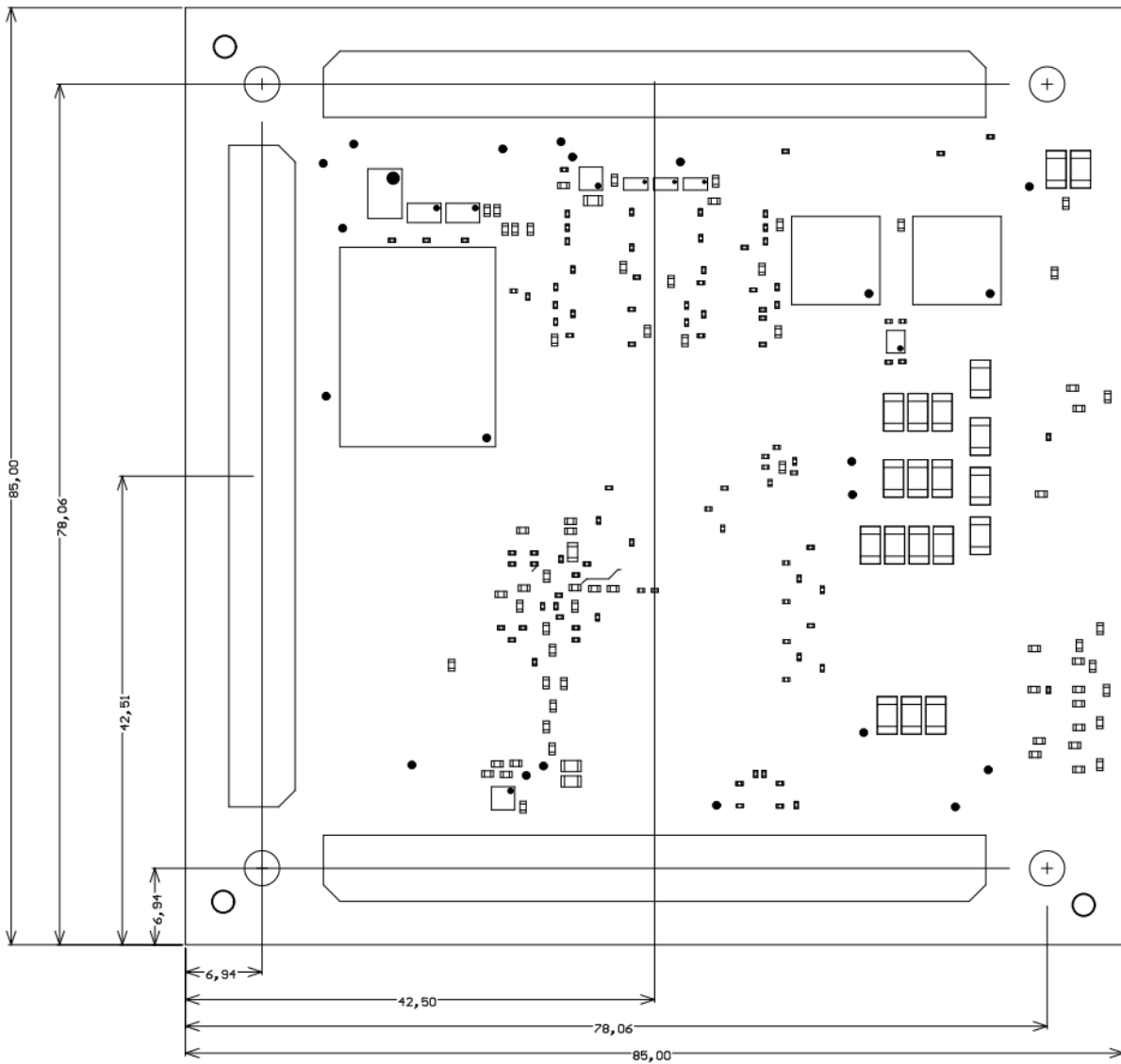
Physical Dimensions

Please download the assembly diagram for exact values.

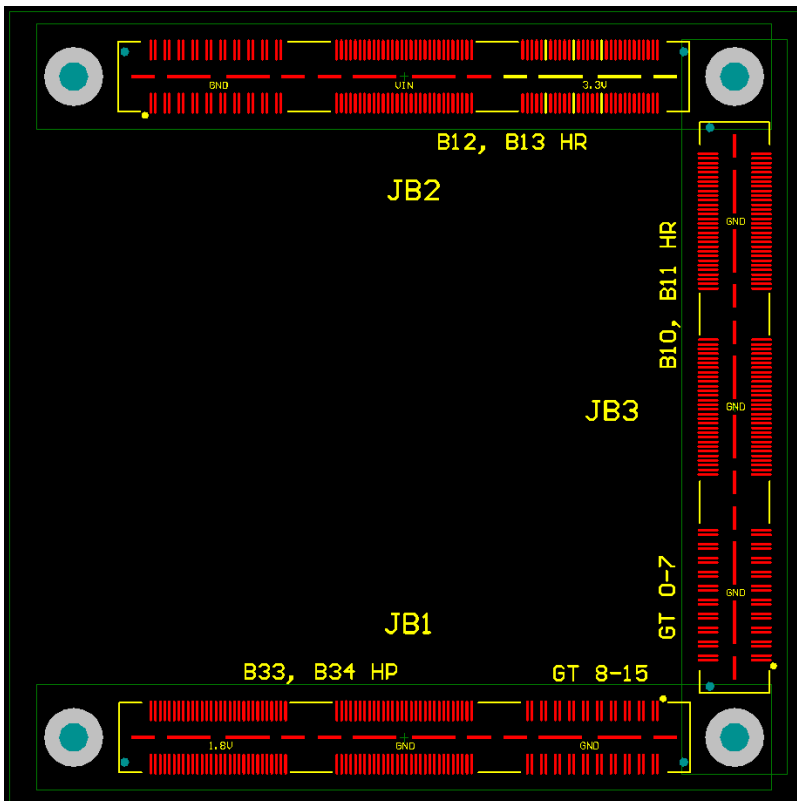
- Module size: 85 mm × 85 mm.
- Mating height with standard connectors: 5 mm
- PCB thickness: 1,7 mm

All dimensions are shown in mm.

Top View



View from the BOTTOM of the module.



View from top onto baseboard for TE0782.

Weight

Weight	Part
60 g	Plain module

Revision History

Hardware Revision History

Revision	Changes
02	First production release
01	Prototypes

Hardware revision number is printed on the PCB board together with the module model number separated by the dash.



Document Change History

date	revision	authors	description
2017-01-24	V12	Ali Naseri	New numbered pictures describing main components added variants in production
2016-12-24			Small corrections
2016-06-27	v10	Ali Naseri, Jan Kumann	Initial release

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REACH, RoHS and WEEE

REACH

Trenz Electronic is a manufacturer and a distributor of electronic products. It is therefore a so called downstream user in the sense of [REACH](#). The products we supply to you are solely non-chemical products (goods). Moreover and under normal and reasonably foreseeable circumstances of application, the goods supplied to you shall not release any substance. For that, Trenz Electronic is obliged to neither register nor to provide safety data sheet. According to present knowledge and to best of our knowledge, no [SVHC \(Substances of Very High Concern\) on the Candidate List](#) are contained in our products. Furthermore, we will immediately and unsolicited inform our customers in compliance with REACH - Article 33 if any substance present in our goods (above a concentration of 0,1 % weight by weight) will be classified as SVHC by the [European Chemicals Agency \(ECHA\)](#).

RoHS

Trenz Electronic GmbH herewith declares that all its products are developed, manufactured and distributed RoHS compliant.

WEEE

Information for users within the European Union in accordance with Directive 2002/96/EC of the European Parliament and of the Council of 27 January 2003 on waste electrical and electronic equipment (WEEE).

Users of electrical and electronic equipment in private households are required not to dispose of waste electrical and electronic equipment as unsorted municipal waste and to collect such waste electrical and electronic equipment separately. By the 13 August 2005, Member States shall have ensured that systems are set up allowing final holders and distributors to return waste electrical and electronic equipment at least free of charge. Member States shall ensure the availability and accessibility of the necessary collection facilities. Separate collection is the precondition to ensure specific treatment and recycling of waste electrical and electronic equipment and is necessary to achieve the chosen level of protection of human health and the environment in the European Union. Consumers have to actively contribute to the success of such collection and the return of waste electrical and electronic equipment. Presence of hazardous substances in electrical and electronic equipment results in potential effects on the environment and human health. The symbol consisting of the crossed-out wheeled bin indicates separate collection for waste electrical and electronic equipment.

Trenz Electronic is registered under WEEE-Reg.-Nr. DE97922676.